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EMC POWERCONNECT

Progress® EMC powerCONNECT

1084.75
Gland EMC powerCONNECT, M75, ø50…63mm



- Suitable for high leakage currents
- Compression sleeve technology
- Direct 360° concentric contact
- -60°C…+100°C
- IP68 up to 10 bar, IP69

PRODUCT DESCRIPTION

Progress® EMC powerCONNECT, with its new, advanced compression sleeve, ensures reliable 360° shield contact in a very compact unit. The direct transfer from the shielding to the cable gland's lower part ensures extremely low transfer resistance.

Low transfer resistance
As a result of the direct contact between the cable's shielding and the cable gland's cone, transfer resistance is very low giving the optimum shield connection required for high leakage current applications.
High leakage currents
The lasting high contact pressure achieved from the fixed compression sleeve and the complete tightening of the middle piece, maximises grounding of leakage currents, the extent of which is limited only by the shield's cross-sectional area.
High flexibility
Excellent sealing performance with high flexibility. The two-part sealing inserts facilitate a large spectrum in the clamping range at a protection class of IP 68 / IP 69.

TECHNICAL DATA

GENERAL DATA

Thread Size (G)	M75
Insert Type	Two-Piece
Cable diameter inner min	50 mm
Cable diameter inner max	56 mm
Cable diameter min	56 mm
Cable diameter max	63 mm
IP class	IP 68 (up to 10 bar), IP 69 further protection

DIMENSIONS

Thread pitch	1.5
Thread length	11 mm
Height (H)	51 mm
Spanner width (AF)	80 mm
Shield diameter max	59.7 mm
Internal cable size	57.9 mm

MATERIALS

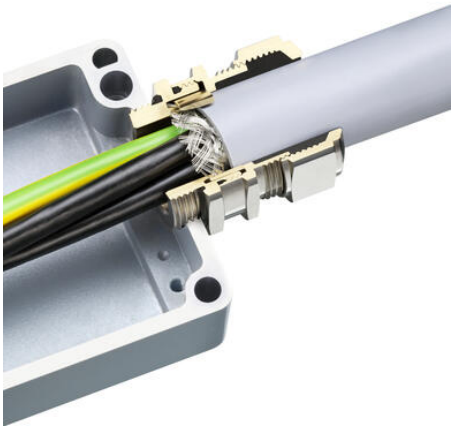
Material	Nickel-plated brass
Materials O-ring	NBR
Material of seals	TPE
Temperature range	-60°C ... +100°C

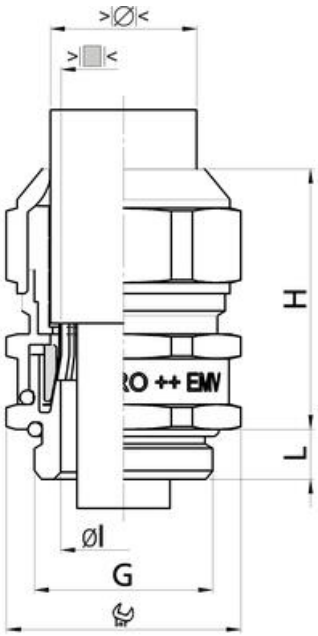
APPROVALS

Approvals	CE, cRUus, DNV, EAC, IEC, VDE
Strain relief	Version A acc. to EN 62444

ADDITIONAL DATA

Pack size	1
Country of origin	CH
Tariff code	74199949
Weight	736 g
Additional features	Approvals in preparation




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